

Title (en)

ELECTROPLATING BATH FOR ELECTROCHEMICAL DEPOSITION OF A CU-SN-ZN-PD ALLOY, METHOD FOR ELECTROCHEMICAL DEPOSITION OF SAID ALLOY, SUBSTRATE COMPRISING SAID ALLOY AND USES OF THE SUBSTRATE

Title (de)

GALVANIKBAD ZUR ELEKTROCHEMISCHEN ABSCHIEDUNG EINER CU-SN-ZN-PD-LEGIERUNG, VERFAHREN ZUR ELEKTROCHEMISCHEN ABSCHIEDUNG VON DIESER LEGIERUNG, SUBSTRAT MIT DIESER LEGIERUNG UND VERWENDUNG DES SUBSTRATS

Title (fr)

BAIN D'ÉLECTRODÉPOSITION POUR LE DÉPÔT ÉLECTROCHIMIQUE D'UN ALLIAGE CU-SN-ZN-PD, PROCÉDÉ DE DÉPÔT ÉLECTROCHIMIQUE DE CET ALLIAGE, SUBSTRAT COMPRENANT LEDIT ALLIAGE ET UTILISATIONS DE CE SUBSTRAT

Publication

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Application

EP 16778284 A 20160930

Priority

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Abstract (en)

[origin: EP3150744A1] The invention provides an electroplating bath for electrochemical deposition of a novel Cu-Sn-Zn-Pd alloy on a substrate. The novel alloy is characterized by exceptional corrosion resistance and the commonly used precious metal intermediate layer (e.g. a Pd-layer) between the substrate and the finishing layer is no longer necessary which allows a substantial reduction of the production costs of the plated substrates.

IPC 8 full level

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Citation (search report)

See references of WO 2017055553A1

Cited by

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